

HD74HC166

Parallel-load 8-bit Shift Register

REJ03D0582-0300

Rev.3.00

Jan 31, 2006

Description

This device is an 8-bit shift register with an output from the last stage. Data may be loaded into the register either in parallel or in serial form. When the Shift/Load input is low, the data is loaded asynchronously in parallel. When the Shift/Load input is high, the data is loaded serially on the rising edge of either clock inhibit or Clock. Clear is asynchronous and active-low.

The 2-input NOR clock may be used either by combining two independent clock sources or by designating one of the clock inputs to act as a clock inhibit.





Features

- High Speed Operation: t_{pd} (Clock to Q_H) = 14 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC166P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74HC166FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)

Note: Please consult the sales office for the above package availability.

Function Table

Inputs						Internal outputs		Output
Clear	Shift/Load	Clock Inhibit	Clock	Serial	Parallel	Q_A	Q_B	Q_H
					A ... H			
L	X	X	X	X	X	L	L	L
H	X	L	L	X	X	Q_{A0}	Q_{B0}	Q_{H0}
H	L	L		X	a ... h	a	b	h
H	H	L		H	X	H	Q_{An}	Q_{Gn}
H	H	L		L	X	L	Q_{An}	Q_{Gn}
H	X	H		X	X	Q_{A0}	Q_{B0}	Q_{H0}

Q_{A0} to Q_{H0} = Outputs remain unchanged.

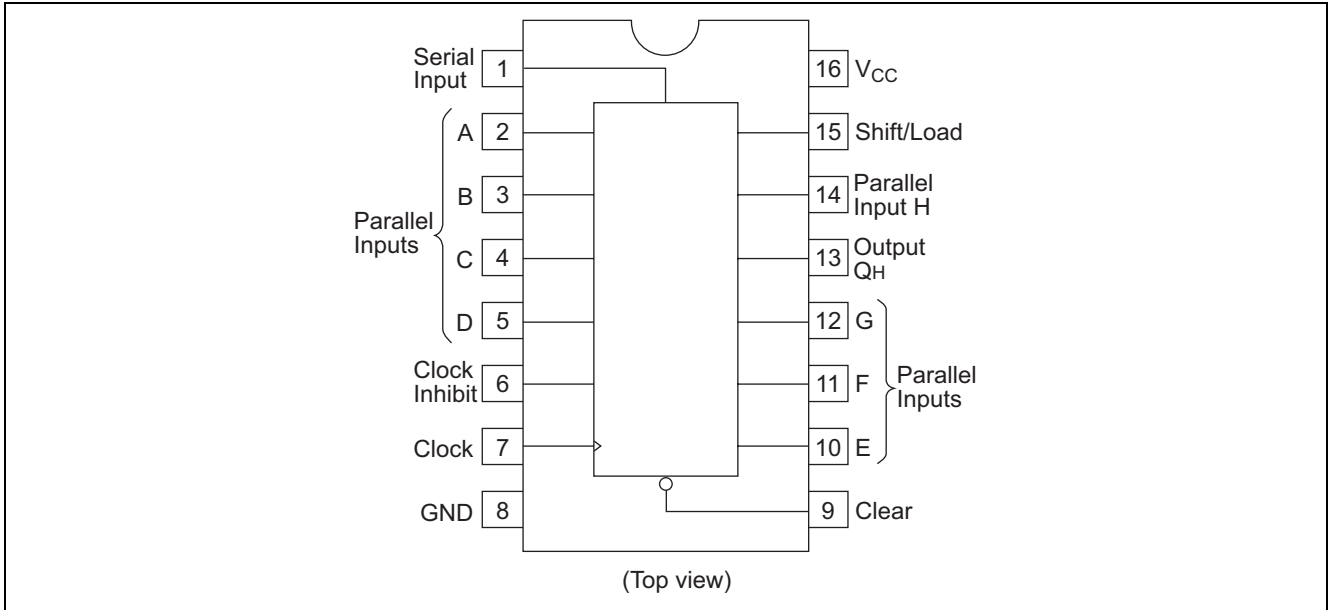
Q_{An} to Q_{Gn} = Data shifted from the previous stage on a positive edge at the clock input.

H : High level

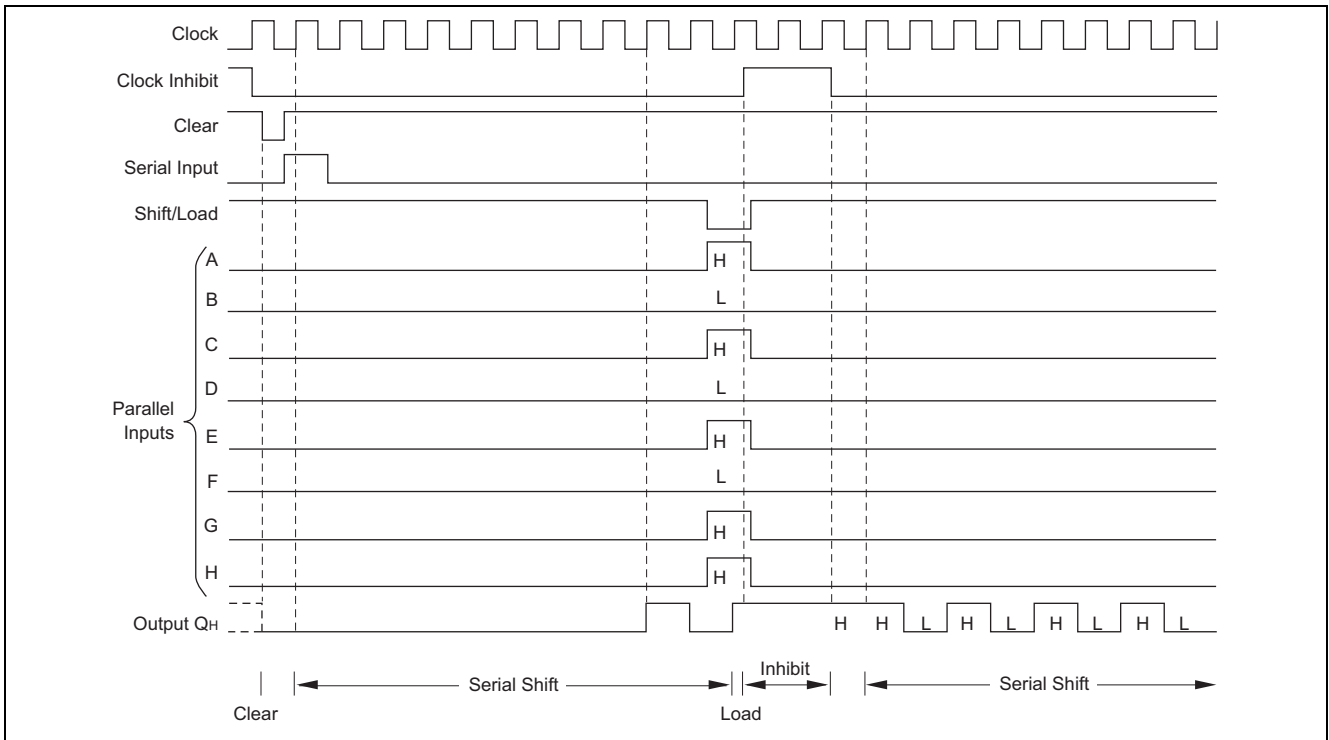
L : Low level

X : Irrelevant

Pin Arrangement



Timing Diagram



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{in}, V_{out}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_O	± 25	mA
V_{CC} , GND current	I_{CC} or I_{GND}	± 50	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	°C

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	2 to 6	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	T_a	-40 to 85	°C	
Input rise / fall time ^{*1}	t_r, t_f	0 to 1000	ns	$V_{CC} = 2.0\text{ V}$
		0 to 500		$V_{CC} = 4.5\text{ V}$
		0 to 400		$V_{CC} = 6.0\text{ V}$

Note: 1. This item guarantees maximum limit when one input switches.
Waveform: Refer to test circuit of switching characteristics.

Electrical Characteristics

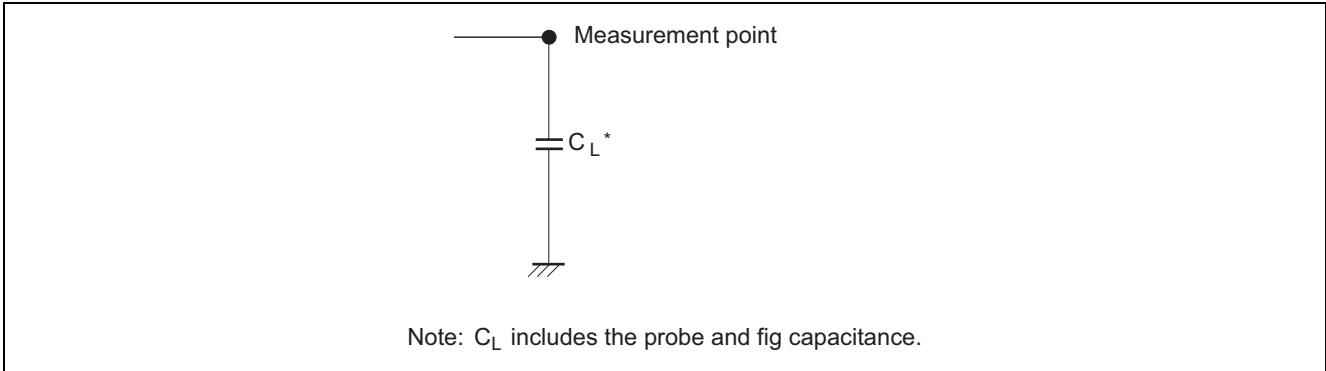
Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40\text{ to }+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V_{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V_{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V_{OH}	2.0	1.9	2.0	—	1.9	—	V	$V_{in} = V_{IH}$ or V_{IL}	$I_{OH} = -20\ \mu\text{A}$
		4.5	4.4	4.5	—	4.4	—			$I_{OH} = -4\ \text{mA}$
		6.0	5.9	6.0	—	5.9	—			$I_{OH} = -5.2\ \text{mA}$
		4.5	4.18	—	—	4.13	—			
		6.0	5.68	—	—	5.63	—			
	V_{OL}	2.0	—	0.0	0.1	—	0.1	V	$V_{in} = V_{IH}$ or V_{IL}	$I_{OL} = 20\ \mu\text{A}$
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			$I_{OL} = 4\ \text{mA}$
		6.0	—	—	0.26	—	0.33			$I_{OL} = 5.2\ \text{mA}$
Input current	I_{in}	6.0	—	—	± 0.1	—	± 1.0	μA	$V_{in} = V_{CC}$ or GND	
Quiescent supply current	I_{CC}	6.0	—	—	4.0	—	40	μA	$V_{in} = V_{CC}$ or GND, $I_{out} = 0\ \mu\text{A}$	

Switching Characteristics

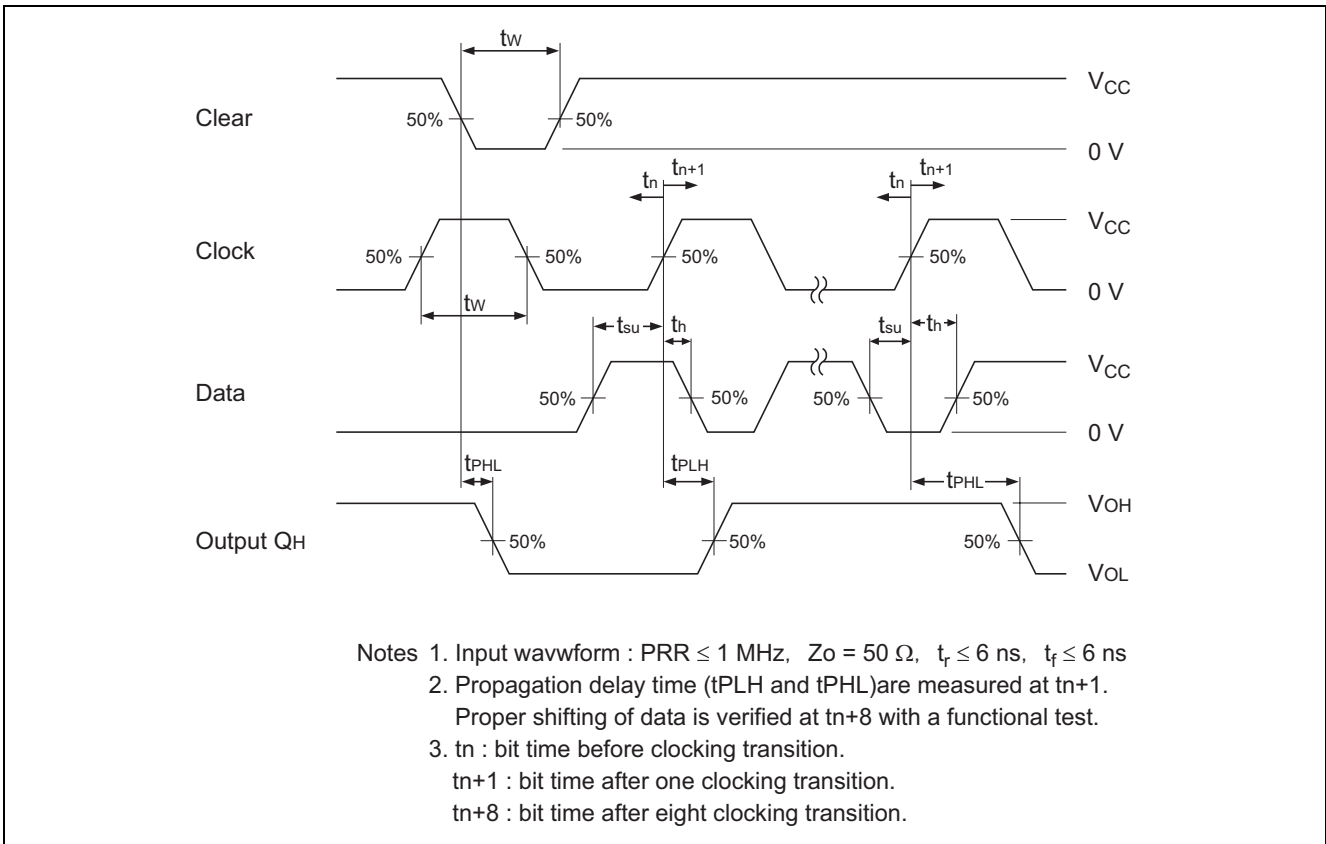
($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40 \text{ to } +85^\circ\text{C}$		Unit	Test Conditions
			Min	Typ	Max	Min	Max		
Maximum clock frequency	f_{max}	2.0	—	—	5	—	4	MHz	
		4.5	—	—	25	—	20		
		6.0	—	—	29	—	24		
Propagation delay time	t_{PHL}, t_{PLH}	2.0	—	—	175	—	220	ns	Clock to Q_H
		4.5	—	14	35	—	44		
		6.0	—	—	30	—	37		
	t_{PHL}	2.0	—	—	150	—	190	ns	Clear to Q_H
		4.5	—	12	30	—	38		
		6.0	—	—	26	—	33		
Setup time	t_{su}	2.0	150	—	—	190	—	ns	Shift/Load to Clock
		4.5	30	2	—	38	—		
		6.0	26	—	—	33	—		
		2.0	100	—	—	125	—	ns	Data to Clock
		4.5	20	1	—	25	—		
		6.0	17	—	—	21	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	Clock to Data
		4.5	5	0	—	5	—		
		6.0	5	—	—	5	—		
Pulse width	t_w	2.0	80	—	—	100	—	ns	Clock, Clear
		4.5	16	6	—	20	—		
		6.0	14	—	—	17	—		
Output rise/fall time	t_{TLH}, t_{THL}	2.0	—	—	75	—	95	ns	
		4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

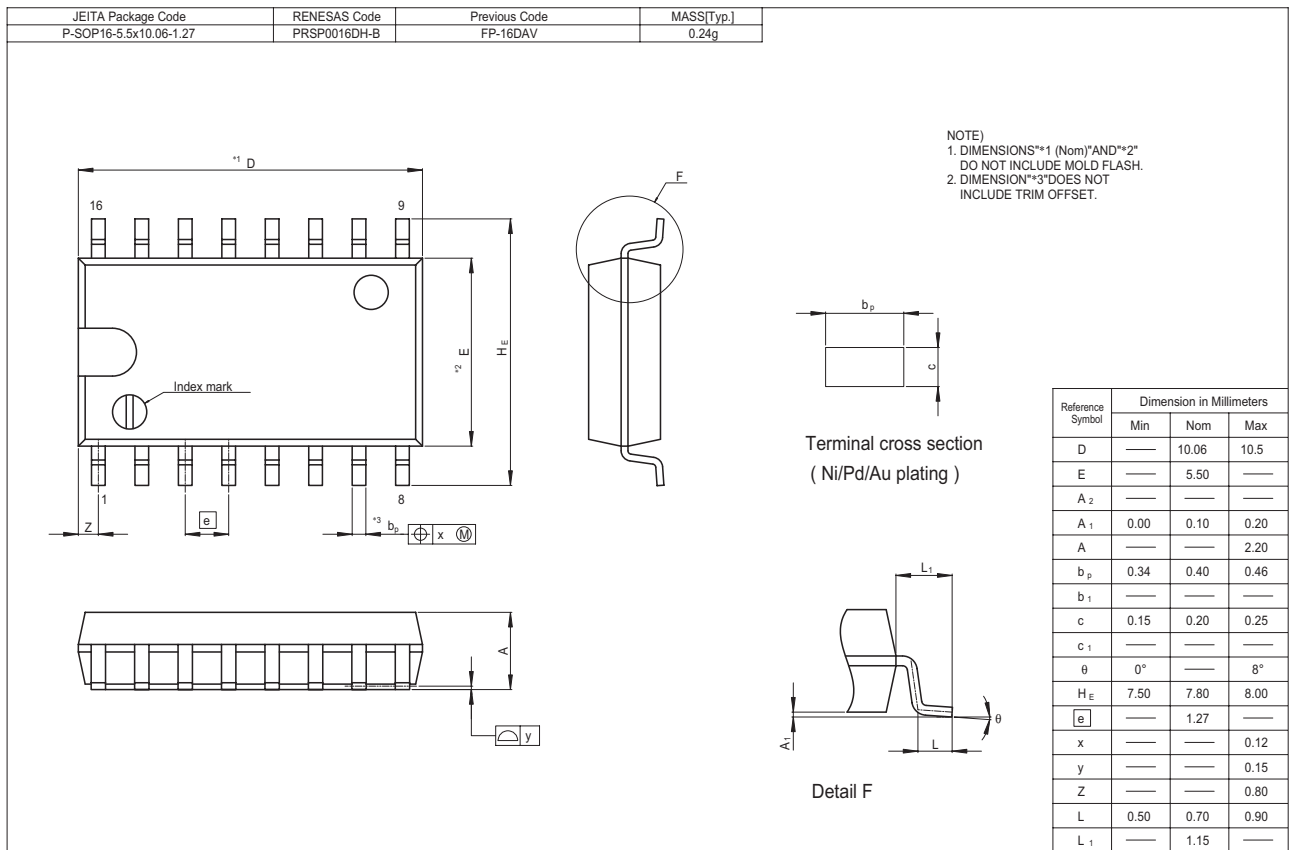
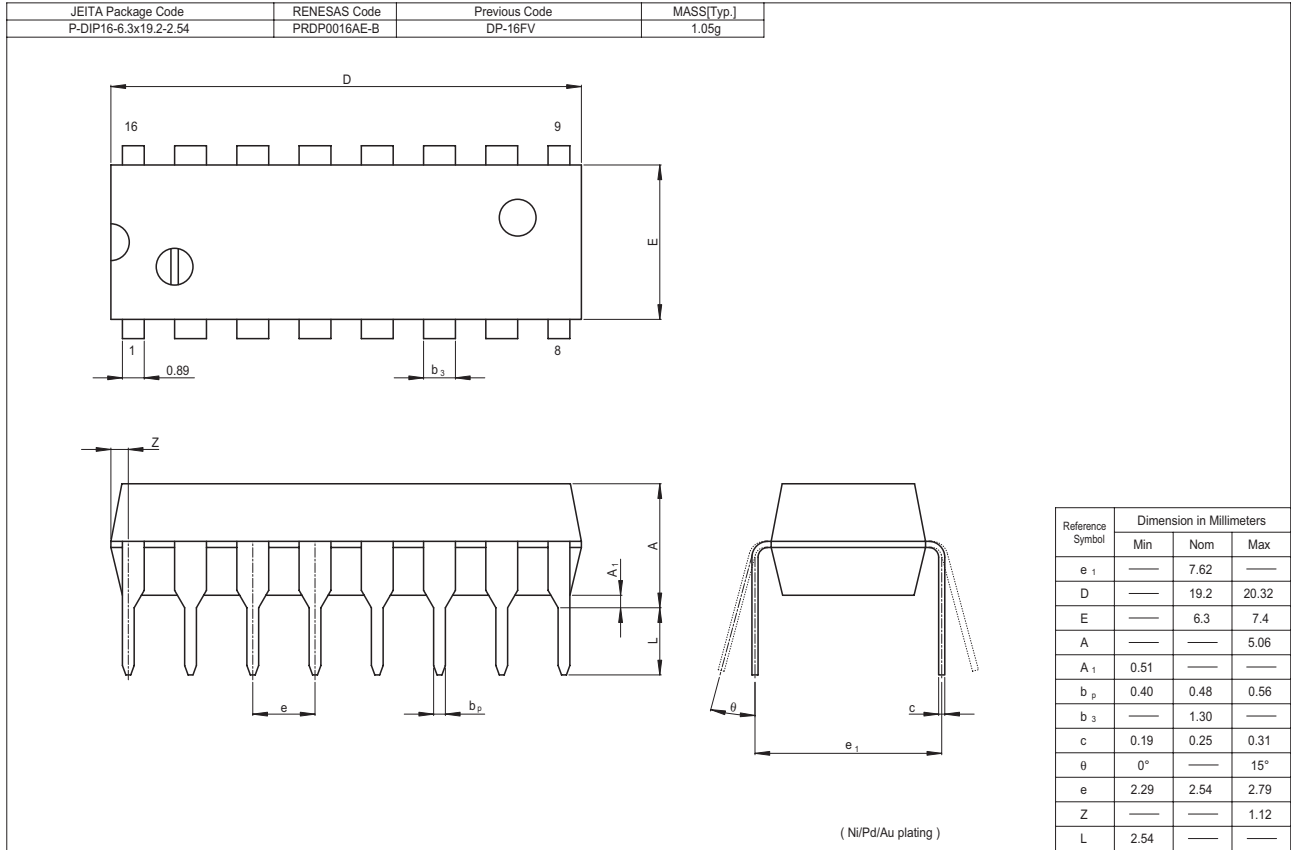
Test Circuit



Waveforms



Package Dimensions



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